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PATENTS

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicant(s):** Yasuaki Tsuchiya, et al.

**Examiner:** Maria Guerrero

**Serial No.:** 09/737,397

**Art Unit:** 2822

**Filed:** December 15, 2000

**Docket:** 14162

**For:** PROCESS FOR FORMING A  
METAL INTERCONNECT

**Dated:** July 26, 2002

Assistant Commissioner for Patents  
Washington, D.C. 20231

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**RESPONSE**

Sir:

In response to the Office Action dated March 26, 2002, applicants submit the following amendment for entry in the above-identified case.

**IN THE CLAIMS:**

Please cancel Claim 29 without prejudice.

Please amend Claims 2, 12 and 28 as follows:

*a'*  
2. (Amended) The process for forming a metal interconnect as claimed in Claim 1, wherein the first polishing step is conducted such that the interconnect metal film remains in 5% to 30% inclusive of the surface area other than the concave.

*Jul 05*  
*92*  
12. (Amended) The process for forming a metal interconnect as claimed in

**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner of Patents and Trademarks, Washington, D.C. 20231 on July 26, 2002.

Dated: July 26, 2002

*[Signature]*  
Michelle Mustafa